3.2x2.4mm SMD CHIP LED LAMP



ATTENTION

OBSERVE PRECAUTIONS FOR HANDLING **ELECTROSTATIC** DISCHARGE SENSITIVE **DEVICES**

Part Number: APBD3224LZGKSYKC

Green Super Bright Yellow

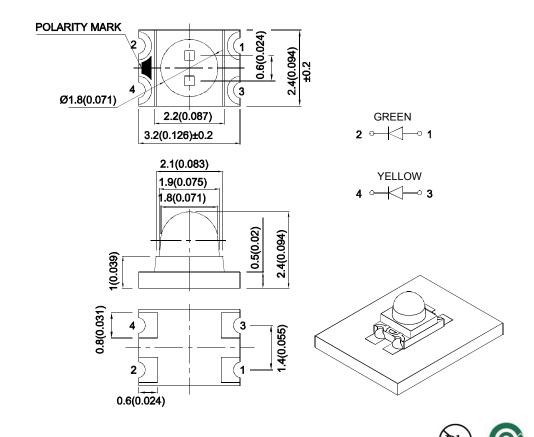
Features

- 3.2x2.4mm SMD LED, 2.4mm thickness.
- Low power consumption.
- Ideal for backlight and indicator.
- Package : 1500pcs / reel.
- Moisture sensitivity level : level 3.
- Low current IF=2mA operating.
- RoHS compliant.

Descriptions

- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode.
- The Super Bright Yellow device is made with AlGaInP (on GaAs substrate) light emitting diode chip.
- Electrostatic discharge and power surge could damage
- It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.1(0.004") unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.

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Selection Guide

Part No.	Emitting Color (Material)	Lens Type	lv (mcd) [2] @ 2mA		Viewing Angle [1]
		-	Min.	Тур.	201/2
APBD3224LZGKSYKC	Green (InGaN)	Water Clear	50	150	- 20°
	Super Bright Yellow (AlGaInP)	vvalei Cledi	20	50	

Notes:

- θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 Luminous intensity/ luminous Flux: +/-15%.
 Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Min.	Тур.	Max.	Units	Test Conditions	
λpeak	Peak Wavelength	Green Super Bright Yellow		515 590		nm	IF=2mA	
λD [1]	Dominant Wavelength	Green Super Bright Yellow		525 590		nm	IF=2mA	
Δλ1/2	Spectral Line Half-width	Green Super Bright Yellow		35 20		nm	IF=2mA	
С	Capacitance	Green Super Bright Yellow		45 20		pF	VF=0V;f=1MHz	
VF [2]	Forward Voltage	Green Super Bright Yellow	2.2 1.5	2.65 1.85	3.1 2.1	V	IF=2mA	
lR	Reverse Current	Green Super Bright Yellow			50 10	uA	VR = 5V	

Notes:

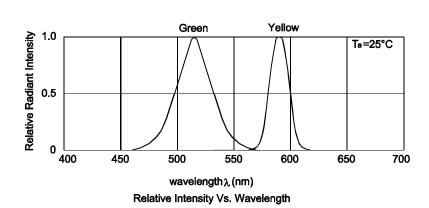
- 1. Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.
- 4. Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

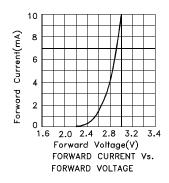
Parameter	Green	Super Bright Yellow	Units	
Power dissipation	77.5	63	mW	
DC Forward Current	25	30	mA	
Peak Forward Current [1]	150	175	mA	
Electrostatic Discharge Threshold (HBM)	450	-	V	
Reverse Voltage		5		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

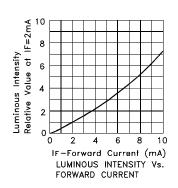
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

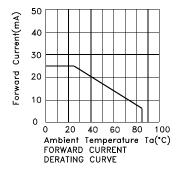
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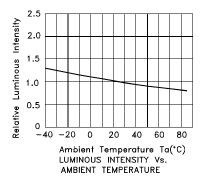


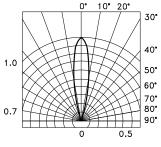
APBD3224LZGKSYKC Green







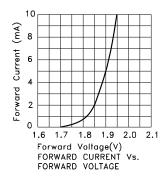


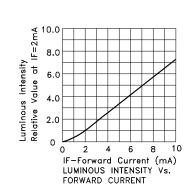


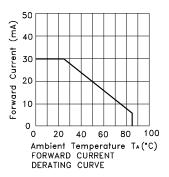
SPATIAL DISTRIBUTION

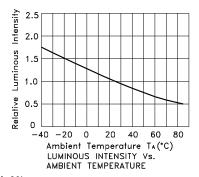
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Super Bright Yellow



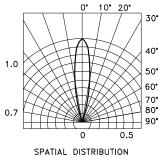






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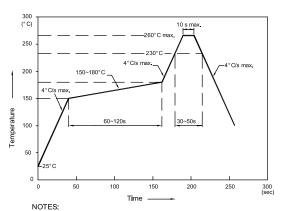


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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

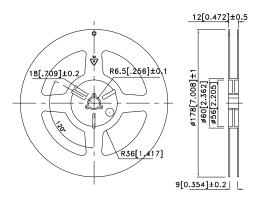


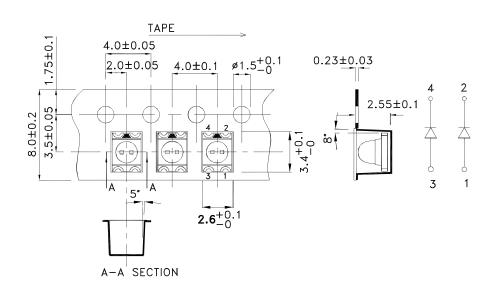
- 1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
- 2.Don't cause stress to the epoxy resin while it is exposed
- to high temperature.
 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

Tape Dimensions (Units : mm)

Reel Dimension



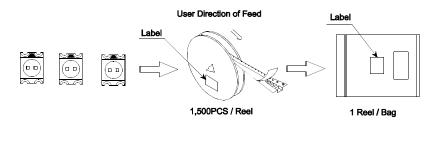


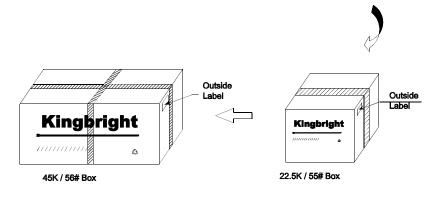
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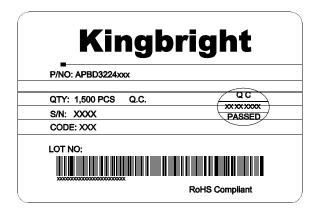


PACKING & LABEL SPECIFICATIONS

APBD3224LZGKSYKC







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